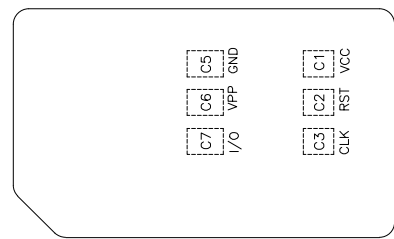
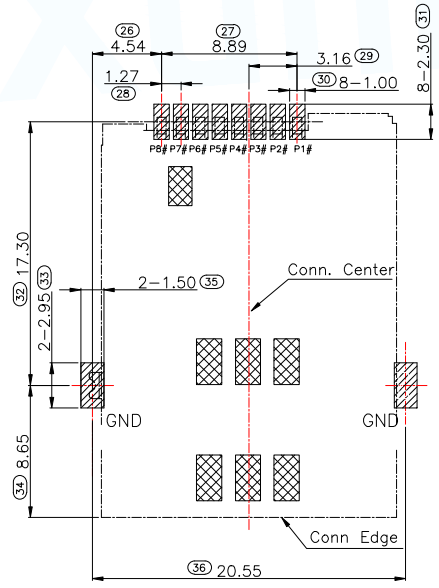
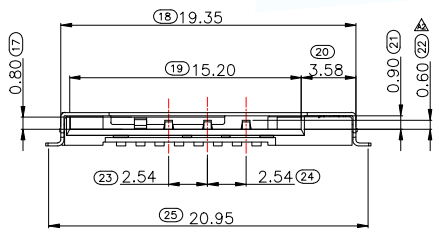


NOTES:
 1) MATERIAL:
 HOUSING: LCP UL 94V-0
 CONTACT: C5210R-H,T=0.15
 SHELL: SUS304,T=0.15
 MYLAR: POLYESTER
 2) FINISH :
 CONTACT:GOLD FLASH PLATED ON CONTACT AREA;
 GOLD FLASH PLATING ON SOLDER TAILS, WITH
 ENTIRE CONTACT UNDERPLATED
 50u"Min,NICKEL
 SHELL: 50u"Min. NICKEL UNDERPLATED OVERALL ,
 GOLD FLASH PLATED ON SOLDER TAILS
 3)INFRARED REFLOW SOLDERING: 10sec. Min. at 260±10

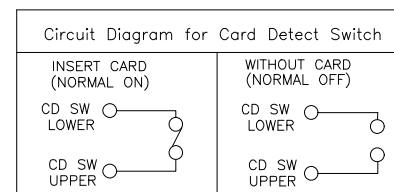


SIM 示意图
芯片面朝下视图

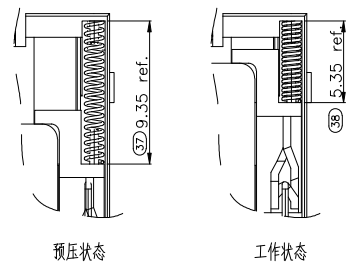


RECOMMENDED PCB LAYOUT(TOP VIEW)
GENERAL TOLERANCES:±0.05

SOLDER AREA
 NONE CIRCUIT DIAGRAM AREA



PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET

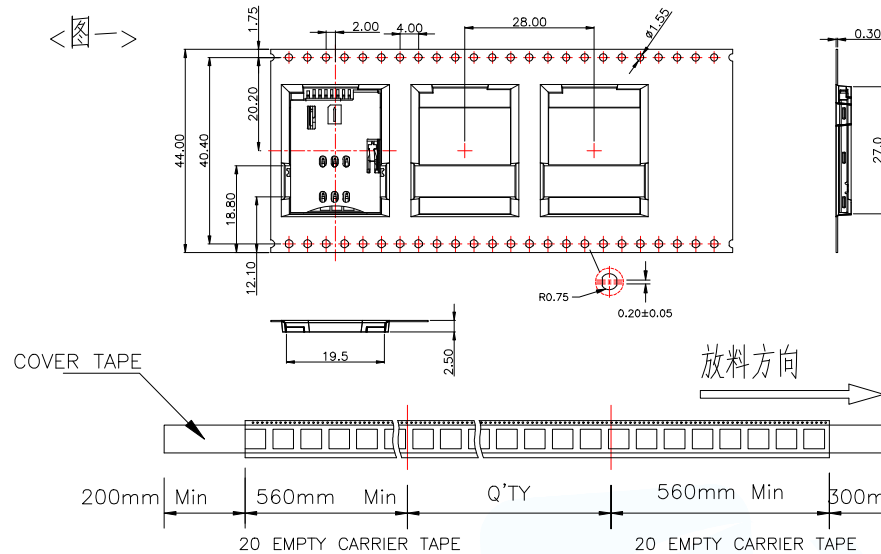


MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	TITLE:2.3H 6+2Pin PUSH PUSH CARD 客户图	
UNLESS OTHERWISE SPECIFIED TOLERANCES			PAR	SIM-130-ARP8H23
DECIMALS:	ANGLES:	DWN		
.X:±0.30	X':±2'	CHKD		
.XX:±0.20	X.X':±1'	APVD		
.XXX:±0.10		SCALE:1:1	UNIT:MM	
		SIZE:A4	SHEET:1F1	
		Website address	REV:A	

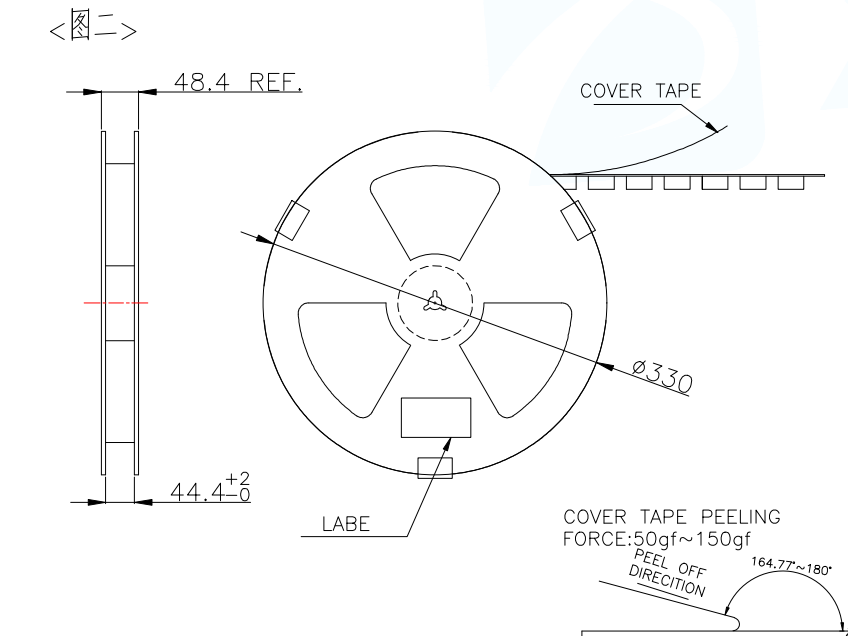
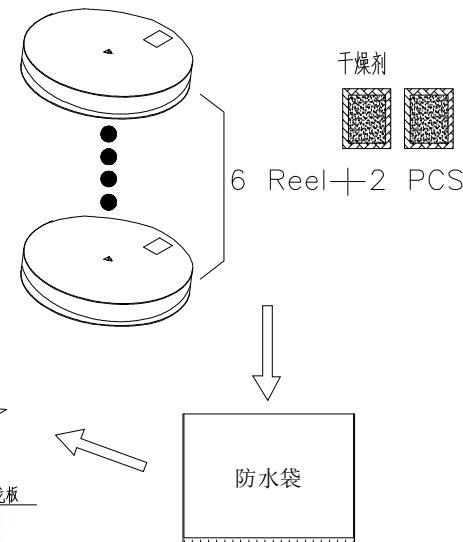
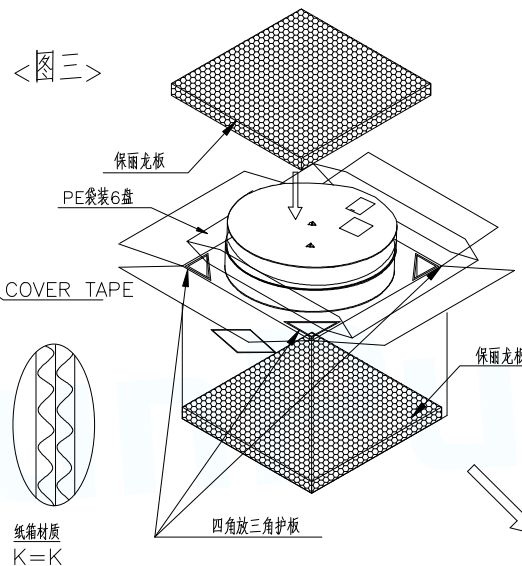


<TABLE 1> PACKAGING QUANTITY

QTY/REEL	REEL/CARTON	QTY/CARTON
550	6	3300

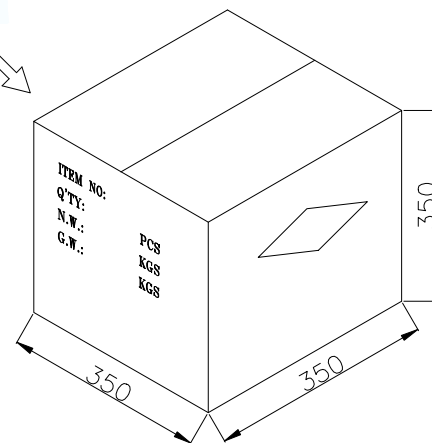


<图三>



备注:

1. 依<图一>示放置产品于Carrier tape中,每穴放置1PCS产品, Carrier tape卷绕时,前端和尾端各需预留20PCS5.
2. Cover tape覆盖Carrier tape前端需超出200mmMIN, 后端需留出300mmMIN, 两端都以美文胶贴固.
3. 包装机包好后,在Reel的个等分点上贴胶带,以防止REEL胀开, 每Reel贴1PCS标签,如<图二>示
4. 包装数量见如<TABLE 1>示
5. 包装成箱见如<图三>示
箱底放保丽龙板,再将PE袋(6个Reel盘, 2PCS干燥剂)放入箱内,四角各放一个三角护板,最上层再放上保丽龙板.
6. 封箱,在封好的纸箱侧面中间位置贴上出货标签.



MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	TITLE:2.3H 6+2Pin PUSH PUSH CARD 客户图	
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.XX:±0.20	X.X':±1'	APVD		
.XXX:±0.10		SCALE1:1	UNIT:MM	
		SIZE:A4	SHEET:1F1	
		Website address	REV:A	